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- (71) Applicant (for all designated States except US): **TOKYO OHKA KOGYO CO., LTD.** [JP/JP]; 150, Nakamaruko, Nakahara-ku,, Kawasaki-shi Kanagawa 211-0012 (JP).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): **TAKAHASHI, Toru** [JP/JP]; c/o TOKYO OHKA KOGYO CO., LTD., 150 Nakamaruko, Nakahara-ku,, Kawasaki-shi, Kanagawa 211-0012 (JP). **KATSUMATA, Naoya** [JP/JP]; c/o TOKYO OHKA KOGYO CO., LTD., 150, Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 (JP). **MAEDA, Hiroki** [JP/JP]; c/o TOKYO OHKA KOGYO CO., LTD., 150, Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa 211-0012 (JP).
- (74) Agents: **TANAI, Sumio et al.**; 2-3-1, Yaesu, Chuo-ku,, Tokyo 104-8453 (JP).
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(54) Title: **CHEMICALLY AMPLIFIED POSITIVE PHOTSENSITIVE THERMOSETTING RESIN COMPOSITION METHOD OF FORMING CURED ARTICLE AND METHOD OF PRODUCING FUNCTIONAL DEVICE**

(57) Abstract: There is provided a photosensitive thermosetting resin composition used for producing a permanent film, capable of forming a resin layer which is excellent in fluidity upon heat bonding after pattern, formation and also has excellent adhesion as well as bonding properties and/or sealing properties. This composition contains a reaction product of (A) an alkali soluble resin and (C) a 10 crosslinking polyvinyl ether compound, (B) a compound generating an acid under irradiation with radiation, and (D) an epoxy resin.

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